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(21) International Application Number: PCT/US96/09672 (22) International Filing Date: 7 June 1996 (07.06.96) (30) Priority Data: 08/483,342 7 June 1995 (07.06.95) US (71) Applicant: THE DEXTER CORPORATION [US/US]; 2850 Willow Pass Road, Pittsburg, CA 94565 (US). (72) Inventors: GEBHARDT, William, F.PAPALIA, Rocco (74) Agents: BRUHN, David, E. et al.; Dorsey & Whitney L.L.P., Pillsbury Center South, 220 South Sixth Street, Minneapolis, MN 55402 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BB, BG, BR, BY, CA, CH, CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>	
(54) Title: METHOD FOR MAKING A DEBOSSSED CONDUCTIVE FILM COMPOSITE			
(57) Abstract A mechanically debossed foil (21) with a circuit pattern is laminated to a thin isotropic uncured and ungelled thermosetting resin film (11). The process comprises debossing a metal foil using a shaping tool with a surface possessing an embossed circuitry pattern, as described in the prior art. The foil (21) is separated from the tool. The separated metal foil (21) is placed in contact with the resin film (11) and forced into the film without significantly altering the foil shape. An optional support layer (18) may be bonded to the film.			